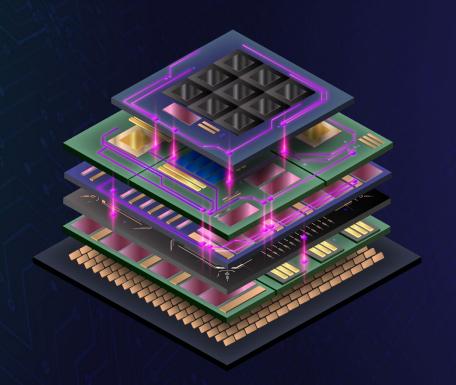
NGMM: The Future is 3DHI

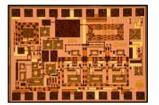
Whitney Mason
Director, Microsystems Technology Office (MTO)
Defense Advanced Research Projects Agency (DARPA)



System on a Chip: State of the Art Today

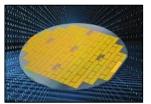


MIMIC: Microwave and Millimeter Wave Monolithic Integrated Circuits



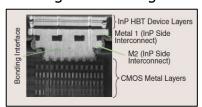
Source: DARPA

WBGS-RF: Wide Band Gap Semiconductor – Radio Frequency



Source: DARPA

DAHI: Diverse Accessible Heterogeneous Integration

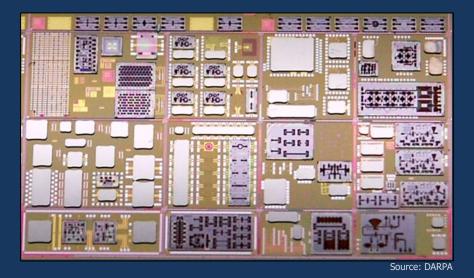


Source: IEEE Microwave

Materials

Si, GaAs, SiGe, GaN

ToolsEUV lithography (ASML)



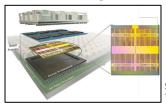
Applications

AI Chips (NVIDIA), iPhone (APPLE), LEO Satcom (StarLink)

Process

Advanced Foundries and Packaging (TSMC)

SMART: Scalable Millimeter-wave Architectures for Reconfigurable Transceivers



Source: DARPA / RTX / Teledyne

VLSI: Very Large-Scale Integrated Circuits



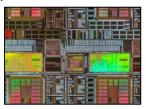
Source: SemiW

Advanced Lithography Tools



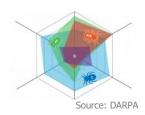
Source: Canon

MOSIS: Metal Oxide Silicon Implementation Service

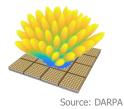


Source: DARPA

UWBGS: Ultra-Wide Band Gap Semiconductors



MIDAS: Millimeter-Wave Digital Arrays



MFRF: Multifunction RF



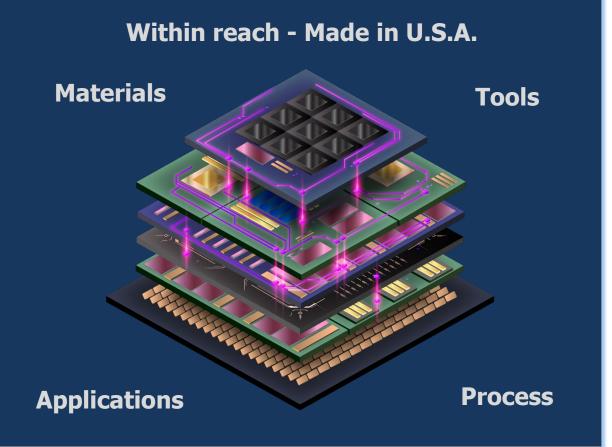
Source: DARPA

FENCE: Fast Event-based Neuromorphic Camera and Electronics

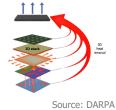


Source: RTX

System on a Chip: NGMM Future



Minitherms3D

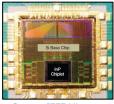




AMME: Additive Manufacturing of MicrosystEms



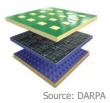
Source: DARPA



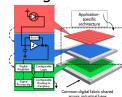
Source: IEEE Microwave

COSMOS: Scalable Millimeter-wave Architectures for Reconfigurable Transceivers

ELGAR: ELectronics for G-band ARrays



ReImagine: Reconfigurable Imaging



Source: DARPA

What Does Success Look Like



